

AMENDMENTS

In the Claims:

1. (Currently Amended) A test socket device adapted for carrying a semiconductor device to be tested, the test socket device comprising:

at least one connection pin, the connection pin being configured to be introduced into a corresponding recess of a contact device of a device to which the socket device is to be connected;

wherein at least one section of the connection pin is made of a resilient material and comprises a curved shape such that a clamping connection is provided between the contact device and the connection pin when the at least one section of the connection pin is introduced into the recess the contact device,

the at least one section has the form of a wave, wherein a first portion of the wave has a first maximum amplitude and a second portion of the wave has a second maximum amplitude, and

the first maximum amplitude and the second maximum amplitude are of different sizes.

2. (Previously Presented) The socket device according to claim 1, wherein the socket device is a semiconductor device testing socket which is configured such that, for testing a semiconductor device, it is loaded with a corresponding semiconductor device.

3. (Previously Presented) The socket device according to claim 1, wherein the socket device is a burn-in socket which is configured such that, for performing a burn-in test, it is loaded with a corresponding semiconductor device.

4. (Canceled)

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Thanks!
Emily
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